





In-Line Root Cause Analysis of Assembly Systems using Artificial Intelligence – Industrial Demonstration

Digital Lifecycle Management (DLM) Research Group 2019-09-24

S. Sinha, E. Glorieux, M. Babu, P. Franciosa, D Ceglarek

INLINE ROOT CAUSE ANALYSIS FOR SHEET METAL PARTS ASSEMBLY

Industry challenge:

• *In-line root cause analysis* of defects using 3D surface scanners.



Case study: 3D-Optical Robotic Scanner



- Increased productivity due to rapid fault diagnosis based on artificial intelligence models
- Continuous quality improvement due to on-line learning and training
- Reduction of dependence on hit and trial based manual expertise





Integrate the knowledge of first engineering principle based <u>Digital Twins</u> and <u>Big Data</u> provided by high dimensional <u>Measurement Systems</u> using <u>Artificial Intelligence</u> to Diagnose Assembly Systems

SYSTEM SETUP





DEMO DEVELOPMENT OVERVIEW





DIGITAL TWIN VALIDATION

Index	Clamp_1	Clamp_2	Clamp_3	Clamp_4	Correlation Between Digital Twin and Actual System
1	0	0	0	0	1
2	-5	0	0	0	0.89
3	5	0	0	0	0.89
4	0	-5	0	0	0.92
5	0	5	0	0	0.88
6	0	0	-5	0	0.97
7	0	0	5	0	0.98
8	0	0	0	-5	0.97
9	0	0	0	5	0.99
Actual System Data					
Digital Tw	vin Data				

Experimentswereconducted between dataobtainedfromsurface scanner and datasimulatedfromdigital twin

After correcting for rigid rotation due alignment, compensating for nonideal part nature and fine tuning digital twin parameters the correlations were calculated



DIGITAL LIFECYCLE INTEGRATION OF DIGITAL TWIN & ARTIFICIAL INTELLIGENCE MANAGEMENT (DLM) MODEL

In-line Root Cause Analysis (After off-line model training and Fine tuning)



The 3D Convolutional **Neural Network Model is** using trained data generated from the validated digital twin until the required accuracy is obtained. The trained model is fine tuned using actual data obtained from the system to compensate difference for the between simulation and actual systems

CATAPUL

ARTIFICIAL INTELLIGENCE MODEL TRAINING IN SIMULATION SPACE







model The converges after **10K** training samples in terms of error metrics such as Mean Absolute Error (MAE) and Mean Squared Error (MSE) well as as fit Goodness of determined by R-Squared Value (R2)



ARTIFICIAL INTELLIGENCE MODEL FINE TUNING & TRANSFER MANAGEMENT (DLM) TO ACTUAL SYSTEM



The model is fine-tuned using the concept of transfer learning bv freezing the weights of the convolutional layers and updating tuning the fully connected layers using a small sample of real data (~ 30 to 90 samples), this has significant improvement in model performance in the actual system

Model Trained and validated by **Digital twin data**

DIGITAL LIFECYCLE



CATAPULI





COMPATIBLE METROLOGY TECHNOLOGIES

NAME	TECHNIQUE	PURPOSE	VIEWPOINTS VS SCANNING
WLS400a (Hexagon)	Stereovision	Dimensional quality	Viewpoints
BLAZE 660A (Hexagon)	Stereovision	Dimensional quality	Viewpoints
RoboticScan (Artec3D)	Stereovision	Dimensional quality	Viewpoints
ATOS 5 (GOM)	Stereovision	Dimensional quality	Viewpoints
ATOS TRIPLE SCAN (GOM)	Stereovision	Dimensional quality	Viewpoints
<u>Gocator (LMI Technologies)</u>	Stereovision	Circuit board inspection	Viewpoints
ARIS (ARIS)	Laser	Dimensional quality	Viewpoints
Dimensional Gauging Perceptron (Perceptron),	Laser	Dimensional quality	Viewpoints
Laser Radar MV331/351 (Nikon Metrology),	Laser	Dimensional quality	Viewpoints
RAPID SCAN (API)	Structured light	Dimensional quality	Viewpoints
<u>COMET Pro AE (Zeis)</u>	Structured light	Dimensional quality	Viewpoints
FlexInspect (ABB),	Structured light	Dimensional quality	Viewpoints
<u>MetraScan3D (Creaform),</u>	Laser	Dimensional quality	Scanning
AirTrack (Kreon)	Laser	Dimensional quality	Scanning
ABIS II (Zeis),	Laser	Surface quality	Scanning

The proposed solutions for *partial measurements* are compatible with <u>all</u> technologies listed in the table above.

The proposed solutions for *coverage path planning and optimisation* as well as for *workpiece placement optimisation* are compatible with <u>viewpoints-based technologies</u>. The proposed solutions for *Root Cause Analysis* are compatible with all technologies that output high Dimensional Cloud of Point Data









Thank-you

Digital Lifecycle Management (DLM) Research Group Please contact <u>Sumit Sinha (email: sumit.sinha.1@warwick.ac.uk</u>) in case of any doubts or colloboration

S. Sinha, E. Glorieux, M. Babu, P. Franciosa, D Ceglarek